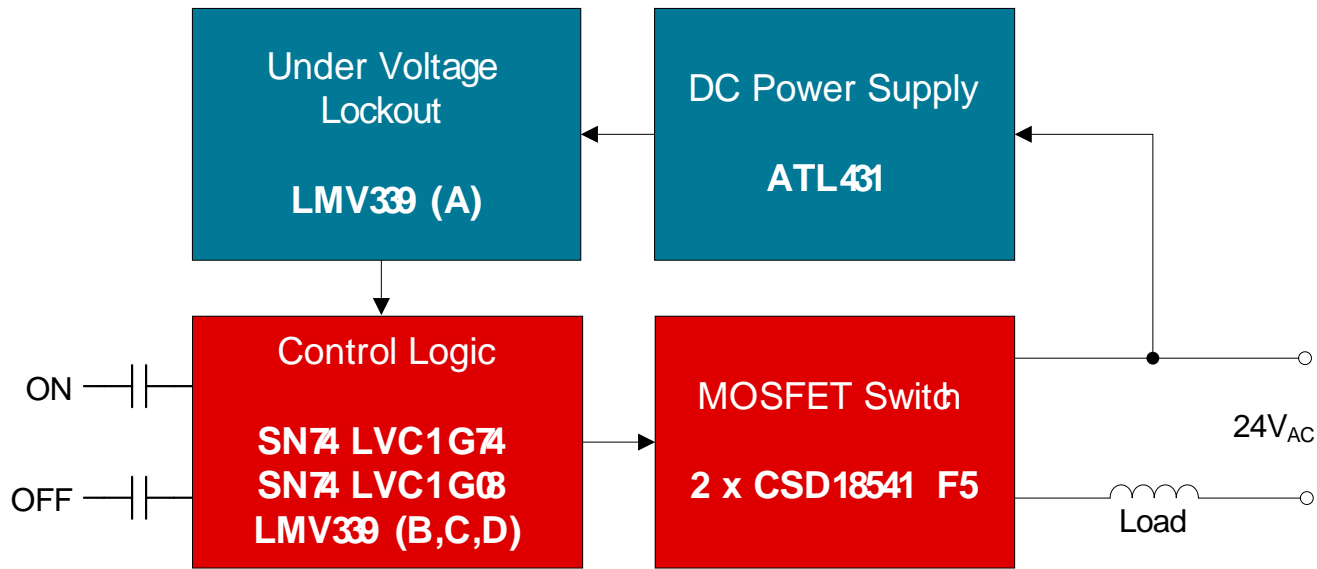


Revision History				
Rev	ECN #	Approved Date	Approved by	Notes
N/A	N/A	N/A	N/A	N/A

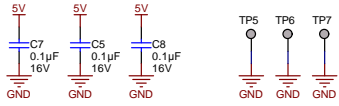
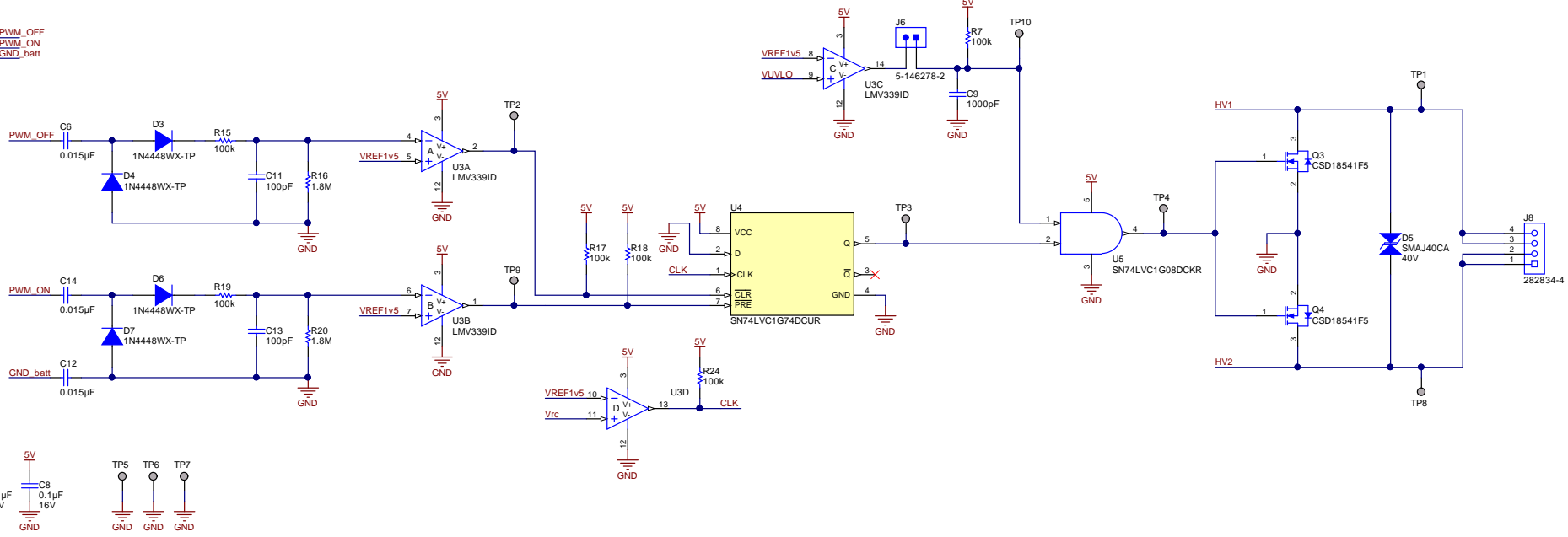
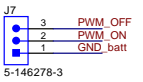
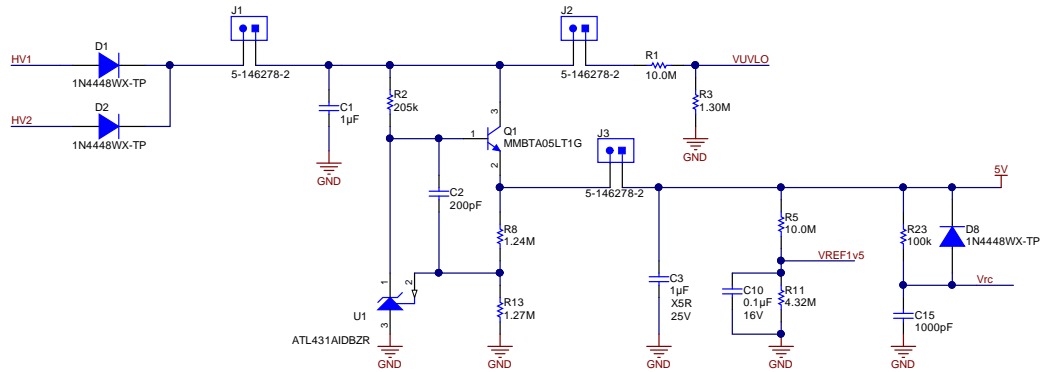


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Orderable: ISBA-EVM-01065	Designed for: Public Release	Mod. Date: 8/25/2016
TID #: TIDA-01065	Project Title: ISBA-EVM-01065	
Number: ISBA-EVM-01065	Rev: Rev	Sheet Title: CoverSheet
Rev: Version control disabled	Assembly Variant: [No Variations]	Sheet: 1 of 3
Drawn By: Tattiana Davenport	File: TIDA-01065 SSR_CoverSheet_SchDoc	Size: B
Engineer: Tattiana Davenport	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	



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TID #: TIDA-01065	Project Title: ISBA-EVM-01065	
Number: ISBA-EVM-01065 Rev: Rev	Sheet Title: TIDA-01065 Schematic	
Version: Version control disabled	Assembly Variant: [No Variations]	Sheet: 2 of 3
Drawn By: Tattiana Davenport	File: TIDA-01065 SSR Relay_SchDoc	Size: B
Engineer: Tattiana Davenport	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	

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H1 1  
NY PMS 440 0025 PH

H2 1  
NY PMS 440 0025 PH

H3 1  
NY PMS 440 0025 PH

H4 1  
NY PMS 440 0025 PH

H5  
1902C

H6  
1902C

H7  
1902C

H8  
1902C

SH-J1

SH-J2

SH-J3

SH-J4

FID1

FID2

FID3

PCB Number: ISA-EVM-01065  
PCB Rev: Rev A

PCB  
LOGO  
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PCB  
LOGO

PCB  
LOGO

ZZ1  
Assembly Note  
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ2  
Assembly Note  
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ3  
Assembly Note  
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Orderable: ISA-EVM-01065		Designed for: Public Release		Mod. Date: 8/25/2016	
TID #: TIDA-01065		Project Title: ISA-EVM-01065			
Number: ISA-EVM-01065		Rev: Rev		Sheet Title: Hardware	
Rev: Version control disabled		Assembly Variant: [No Variations]		Sheet: 3 of 3	
Drawn By: Tattiana Davenport		File: TIDA-01065_SSR_TID_Hardware_SchDoc		Size: B	
Engineer: Tattiana Davenport		Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>			

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